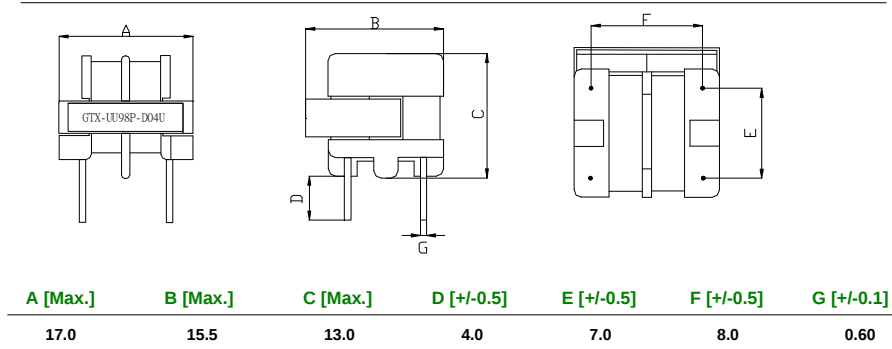
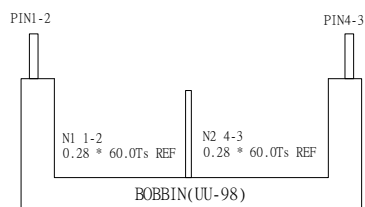


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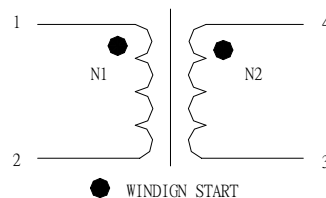
DIMENSION : [mm]



WINDING CONSTRUCTION :



SCHEMATIC :



NO	WINDING	TERMINAL	WIRE	TURNS
1	N1	1-----2	0.28 mm	60.0 Ts
2	N2	4-----3	0.28 mm	60.0 Ts
MATERIAL				
DESCRIPTION	MATERIAL	MANUFACTURER		UL NO.
CORE	UU9.8	CHENGDUHENG L I MAGNETIC MATERIALS CO., LTD.		
BOBBIN	PHENOLIC UU9.8	CHANG CHUN PLASTICS CO., LTD OR EQU.		E59481
WIRE	2UEW	HENG YA ELECTRIC KUN SHAN CO., LTD.		E245514
TAPE	PZ-280	YA HUA		E16511
VARNISH	JX-1150(a)	YUEYANG GREEN TECHNOLOGY CO., LTD.		E303754
ELEC. SPEC				
L (1 - 2) (4 - 3) (1KHz / 0.25V)	HI-POT N1/N2 (50Hz / 3mA / 1sec)	HI-POT N1/N2-CORE (50Hz / 3mA / 1sec)	INSULATION RESISTANCE N1-N2 ; N1/N2-CORE	DCR(1 - 2) (4 - 3) Max.
5.6 mH Min.	AC 1.0 KV	AC 1.0 KV	DC 500V / 100M Ohm min.	1.4 Ohm
TEST CONTITION				
1. LCR meter CH1061				
2. Operating Temperature : -40℃ ~ + 85℃.				

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Reliability Test Result :																			
NO	ITEM	TEST CONDITIONS	REMARKS																
1	Thermal Shock (Temperature Cycle) 溫度循環試驗	Temperature:-40 ° C/ +85 ° C kept stabilized for 30 minutes each Cycle: 100 Cycles	There must be no deformation or change in dimension. Inductance must not change more than the stated tolerance.																
2	Humidity Resistance 耐濕試驗	Humidity: 90%~ 95% RH Temperature: 40± 2 ° C Test Time: 500± 12 Hours	There must be no case deformation or change in dimensions. Inductance must as specification stated.																
3	High Temperature 耐熱試驗	Temperature: 85± 2 ° C Humidity: 20% Test Time: 500± 12 Hours	There must be no case deformation or change in dimensions. Inductance must as specification stated.																
4	Low Temperature 耐寒試驗	Temperature: -40 ± 2 ° C Test Time: 500± 12 Hours	There must be no case deformation or change in dimensions. Inductance must as specification stated.																
5	Temperature and Humidity Cycle 溫/濕度循環試驗	<table border="1"> <thead> <tr> <th>Step</th><th>Temp</th><th>Humidity</th><th>Time</th></tr> </thead> <tbody> <tr> <td>1</td><td>25± 2 ° C</td><td>95~100%RH</td><td>3.0Hr</td></tr> <tr> <td>2</td><td>55± 2 ° C</td><td>95~96%RH</td><td>9.5Hr</td></tr> <tr> <td>3</td><td>25± 2 ° C</td><td>95~100%RH</td><td>9.5Hr</td></tr> </tbody> </table>	Step	Temp	Humidity	Time	1	25± 2 ° C	95~100%RH	3.0Hr	2	55± 2 ° C	95~96%RH	9.5Hr	3	25± 2 ° C	95~100%RH	9.5Hr	There must be no case deformation or change in dimensions. Inductance must as specification stated.
Step	Temp	Humidity	Time																
1	25± 2 ° C	95~100%RH	3.0Hr																
2	55± 2 ° C	95~96%RH	9.5Hr																
3	25± 2 ° C	95~100%RH	9.5Hr																
6	Vibration 振動性試驗	Frequency: 10Hz~50Hz Amplitude: 1.5mm Direction: X,Y,Z Time: 2 Hours each	Solder inductors on the test PCB.After vibration, there must be no deformation or change in dimension. Inductance must not change more than the stated tolerance.																
7	IR Reflow Soldering 焊錫性試驗	Solder: H63A(eutectic solder) Solder Temp.: 232± 5 ° C Time: 6 minutes Cycles: x 1	Inductance shall be within ± 20% of the initial value. DCR value shall be within ± 20% of the initial value.																
8	Soldering Heat Resistance 耐熱 焊性試驗	Preheat:120 ~ 150 ° C (60 sec) Solder:H63A(eutectic solder) Solder Temp.: 260 ± 5 ° C Flux: Rosin Dip time: 10± 1 seconds	The chip must have no cracks.More than 75% of the terminal electrode must be covered with solder. For 96.5 Sn / 3.5 Ag Solder Past: > 217 ° C / 90 Seconds. For 63.0 Sn / 37 Pb Solder Past: > 183 ° C / 120 Seconds.																

BOX Package: cm

